

EV Group Earns Ninth Triple Crown Win in VLSIresearch 2021 Customer Satisfaction Survey – July 14, 2021

semiconductor packaging news

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July 14, 2021

[The U.S.-China Tech Conflict Goes Through Belgium](#)

The historic Belgian city of Leuven is known for its centuries-old university and as the headquarters of brewing giant Anheuser-Busch InBev NV. Less so as the location of a semiconductor research organization that is now the center of both political and industry attention. The Interuniversity Microelectronics Centre, or imec, may be Belgium's best-kept secret, but it's in global demand ...

[Bloomberg](#)



[2x Faster, 1/2 the Capital Cost, 1/2 the Footprint](#)

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate. [Yield Engineering Systems, Inc.](#)



[Thermally Conductive Epoxy for Potting](#)

Master Bond EP29LPAO is a two component thermally conductive, electrically insulative epoxy suited for potting and encapsulating, even in large volumes. [Master Bond](#)



[China's chip imports soar in June as manufacturers build up supply amid global shortage](#)

China's semiconductor imports continued to grow at a fast clip in June, meeting the country's huge demand for integrated circuits (ICs) used in the production ...

[South China Morning Post](#)

[CF4-free Microwave Induced Plasma Decapsulation of Automotive Semiconductor Devices](#)

Multiple case studies are discussed that address challenging automotive semiconductor device decapsulation, including bare Cu wire, Cu-RDL, exposed power copper ...

[Technical Paper](#)

[TSMC dossier \(4\): Technology contention among world-class leaders](#)

Intel claims that TSMC's 7nm process is the equivalent of Intel's 10nm process. This may be true in terms of tech specs but Intel hasn't really outraced still TSMC. ...

[Digitimes](#)

Technical Papers

- [Thermocompression Bonding: Process and Challenges](#)
- [Power Modules: Typical Failure Modes and how to Avoid them](#)
- [Die Attach for 5G Designs](#)
- [Will an Adhesion Promoter Prevent Delamination in Power Semiconductor Packages?](#)
- [Innovations in Wire Bond Inspection](#)
- [Customized Assembly Process for Hermetic Devices](#)
- [CF4-free Microwave Induced Plasma Decapsulation of Automotive Semiconductor Devices](#)

Hermetic Lowest Fine Leak Rates

Developing a leak test process for hermetic sealed packages involves numerous steps. Most important is a process which will identify gross leaks so fine leak rate data is accurate. Read more. [MicroCircuit Laboratories LLC](#)



Today's Sponsor



Test Your Knowledge

What part of our brains typically handles process-type functions, according to brain theorists such as Katherine Benziger? See answer below.

Licensed Manufacturing Solutions

When continuity of supply is vital, we are a licensed semiconductor manufacturer with a full range of semiconductor manufacturing services and solutions. [Rochester Electronics](#)



Press Releases

[EV Group Earns Ninth Triple Crown Win in VLSIresearch 2021 Customer Satisfaction Survey](#)

EV Group (EVG) announced that it has once again been voted by customers as one of the 10 BEST Focused Suppliers of Chip Making Equipment and one of the 2021 THE BEST Suppliers ...

[EV Group](#)

[Teledyne Relays Announces Four New Reed Relay Families](#)

Teledyne Relays announced availability of four new reed relay product families, all offering extremely long life of up to 1 billion cycles, ideal for applications where high reliability ...

[Teledyne Defense Electronics](#)

[3D Stacking Paves Way For Smaller, Power-Packed Computing Chips](#)

Scientists from the Institute of Microelectronics (IME) at the Agency for Science, Technology and

Choices of Dynastrip® Removers

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Sonix, Inc.



Taiwan Maintains Edge as Largest Base for IC Wafer Capacity

As a percent of worldwide total, China achieves largest increase in fab capacity at expense of all other regions, but still trails Taiwan, South Korea, and Japan in installed ...

IC Insights

CORONAVIRUS/TSMC encouraging remote work amid COVID-19

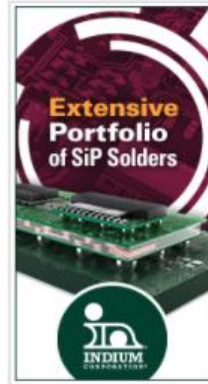
Taiwan Semiconductor Manufacturing Co. (TSMC) reported three confirmed COVID-19 cases, but the company said a day later that it has taken extensive measures ...

Focus Taiwan

Manufacturing Bits: July 13

At the recent 2021 IEEE 71st Electronic Components and Technology Conference (ECTC), a group presented a paper on the development of a wafer-level fan-out package ...

Semiconductor Engineering



Taiwan 2nd-tier OSATs to embrace bright prospects for 2H21

Taiwan's second-tier IC backend houses are set to embrace brisker business results for the second half of the year thanks to a significant surge in customer orders, ...

Digitimes

Three months, 700 steps: Why it takes so long to produce a computer chip

Christopher Belfi was waiting tables in a lakeside resort near this upstate New York town a decade ago when he got the career break he'd been waiting for -- an invitation ...

The Seattle Times

China set to achieve 14 nm breakthrough in 2022

China consumes about 70% of global semiconductor production. But the country's plans to mass produce 14 nm chips next year within the country is likely to make ...

Total Telecom

Eliminate Gold Embrittlement!

We use automated robotic hot solder dip equipment for gold mitigation on SMT & through-hole devices. Gold plating is removed and replaced with tin-lead solder. Learn more.

Circuit Technology Center



Backside Metallization

Advanced semiconductor packaging requirements for higher and faster performance continue to be the driver for mining and artificial intelligence (AI)/high performance computing (HPC) applications.

JCET



Week In Review: Auto, Security, Pervasive Computing

The IoT designer Deed designed a screenless health monitor, worn on the wrist, that uses IoT (Internet of Things) building blocks from Infineon Technologies. ...

Semiconductor Engineering

Research (A*STAR) have developed breakthrough technology that can stack up to four layers ...

Institute of Microelectronics

Pb-free high-temp solder (m.p. 280°C)

With our unique precious metal powdering and pasting technology, AuSn paste is most suitable paste material for high strength and high reliability bonding applications.

Mitsubishi Materials



Quote of the Day

"Being right half the time beats being half right all the time."

Herbert Browne

Pb-free high-temp solder (m.p. 280°C)

With our unique precious metal powdering and pasting technology, AuSn paste is most suitable paste material for high strength and high reliability bonding applications.

Mitsubishi Materials



Precious Metals Deposition Services

Gold, Palladium, Platinum, & Silver thin films for biomedical, electronic, & optical applications. Available on a variety of substrates: polymer, semiconductor, or metal pieces.

Hionix



What Year Was It?

French Revolutionaries Storm Bastille

Parisian revolutionaries and mutinous troops storm and dismantle the Bastille, a royal fortress that had come to symbolize the tyranny of the Bourbon monarchs.

The day was Jul 14. What year was it?



Tungsten Copper (W-CU) Heat Sinks for IC packages

Low CTE ($8.2 \times 10^{-6}/K$). High thermal conductivity (180 ~ 200 W/mk) gold plating, nickel plating or oxidation resistance treatment is available.

Malico Inc.



PacTech's SB²-SMs Quantum

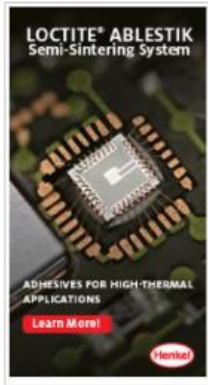
The SB²-SMs Quantum brings contactless & fluxless soldering technology into 3D component soldering. For automated sequential laser soldering, catering to microelectronic devices.

PacTech



Cartoon of the Day





"Either lead, follow, or get out of the way. But never try to do all three at the same time!"
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Calendar

- [Jul 22, 2021: Overview of Semiconductor Manufacturing Webinar for American Attendees](#)
- [Jul 27, 2021: VIRTUAL: Copper and Gold Wire Bonding](#)
- [Jul 27, 2021: FREE Webinar - Solder Mask and Low Stand-off Component Cleaning -- A Connection?](#)
- [Aug 3, 2021: VIRTUAL: Capacitor Reliability Seminar](#)

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We use automated robotic hot solder dip equipment for gold mitigation on SMT & through-hole devices. Gold plating is removed and replaced with tin-lead solder. Learn more.
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Die-Attach Adhesives for Productivity

Low moisture absorption proven to meet AEC Grade-0 and MSL Level-1 reliability. Wafer level applicable DAF. Up to 250° wire-bonding and rapid curable for ultimate productivity.
AI Technology, Inc.



Test Your Knowledge Answer

What part of our brains typically handles process-type functions, according to brain theorists such as Katherine Benziger?
Answer: Left Basal (left rear)

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